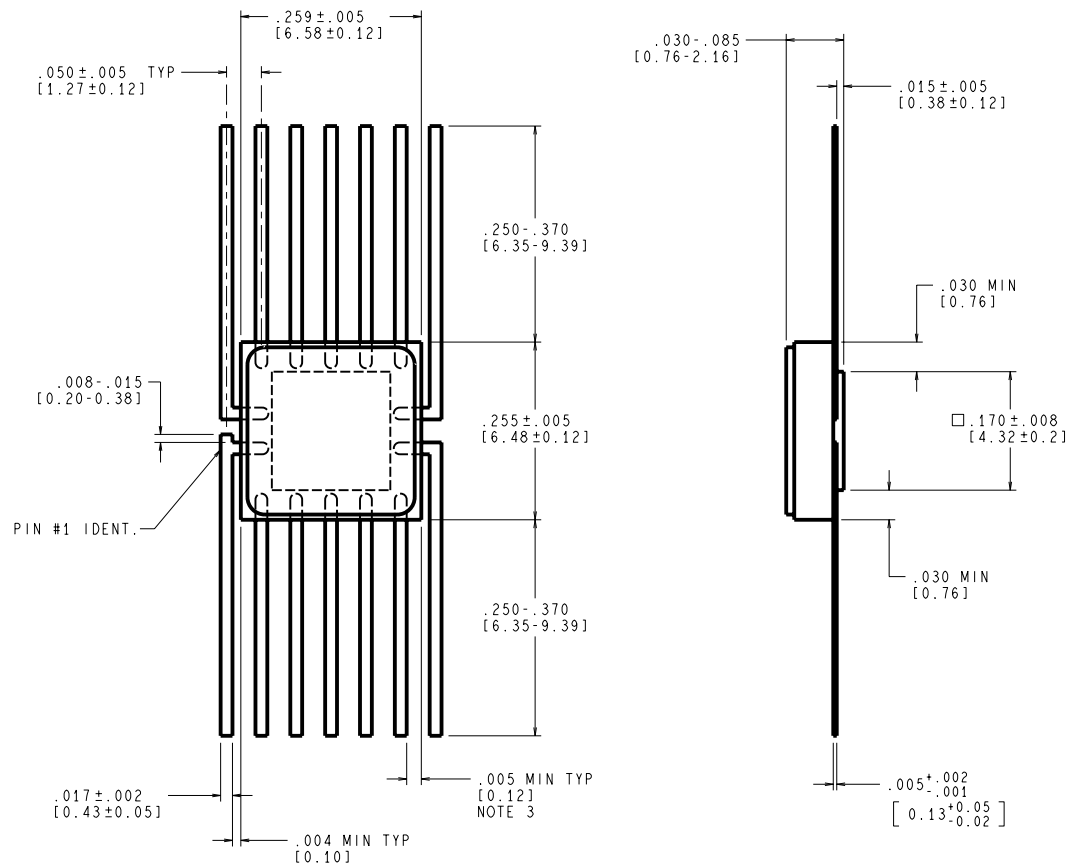




CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. LEAD FINISH TO BE THE FOLLOWING:
50-100 MICROINCHES / 1.27-2.54 MICROMETERS GOLD
OVER 50-350 MICROINCHES / 1.27-8.89 MICROMETERS
NICKEL UNDERPLATE.
2. LEAD FINISH, NICKEL UNDERPLATE AND BASIS METAL
SHALL CONFORM TO THE REQUIREMENTS OF MIL-M-38510.
3. DIMENSION .005 IN / 0.13mm MINIMUM SHALL BE MEASURED
FROM THE EDGE OF THE FURTHEST EXTENSION OF THE METAL
PAD OR LEAD.
4. NO JEDEC REGISTRATION AS OF 03-31-94.

REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
J	REVISE AND REDRAW PER NEW STANDARD	10384	06/02/94	MS/

MIL-M-38510
CONFIGURATION CONTROL

MIL/AERO
CONFIGURATION CONTROL

APPROVALS		DATE		NATIONAL SEMICONDUCTOR CORPORATION 2900 Semiconductor Drive, Santa Clara, CA 95052-8090	
DRAWN <i>MARTA SUCHY</i>		06/02/94			
DFTG. CHK.					
ENGR. CHK.					
APPROVAL				FLATPACK, CERAMIC, 14 LEAD	
PROJECTION [INCH [MM]		SCALE N/A	SIZE C	DRAWING NUMBER MKT-F14C	REV J
DO NOT SCALE DRAWING				SHEET 1 of 1	